





>>> RADAR TECHNOLOGY >>> DEFENSE SYSTEMS >>> AEROSPACE >>> SECURITY APPLICATIONS





WITH THE RIGHT SYSTEM FOR A SECURE FUTURE

Thermal processes with or without vacuum

Reliable connections for high-mass components

- > High heat transfer
- › Large masses
- > Small delta T
- > Process reliability
- > Void-free soldering

Soldering of electronic assemblies with vacuum for void reduction

- > Lower operating temperatures
- > Better heat transfer
- > Prolonged service life

The 3-in-1 solution for safe soldering processes - even for complex boards

- > Safe process design
- High flexibility for profiling



Condenso | Condensation soldering



VisionXP+ Vac | Convection soldering



TripleX | Convection soldering

Your partner for

Defense and security

As a technology leader in thermal system solutions for the electronics industry, we are a global partner in high-tech equipment for the defense and security sector.

When it comes to manufacturing defense and security electronics as well as high-performance electronics for communication or surveillance technologies, our customers rely on Rehm's experience. With our innovative solutions in the areas of bonding, sealing, protecting, drying, curing, reflow soldering, deoxidation, testing and inspection, we offer technologies for your individual requirements and beyond.

Whether automation, cluster solutions or traceability - Rehm is your partner for the common path.

- > 7000

 Production machines in the field
- > 600 creative minds for your requirements
- > 33
 Years technology leader
- Process areas for your technology

Material application and drying | Curing

Various material application methods

- \rightarrow Bonding, dispensing and potting
- > Selective conformal coating
- → 3D Filling

- > Micro-dispensing
- > Bonding of SMD components
- → Underfill



Protecto | Coating

RDS UV | Drying/curing

